AMENDMENT TO THE CLAIMS

1. (Deleted) A system comprising:
a scavenging blade;
a printed wiring board receiving portion; and
a movement mechanism adapted to move the scavenging blade and printed wiring board receiving portion relative to each other;
wherein the scavenging blade is positioned to interpose itself between a printed wiring board positioned in the receiving portion and at least some excess fill material on the printed wiring board during such relative movement.

2. (Deleted) The system of claim 1 wherein the system is adapted to remove fill material which accumulates on the blade during the relative movement of the scavenging blade and printed wiring board.

3. (Deleted) The system of claim 1 wherein the system comprises a printed wiring board positioned on the printed wiring board receiving portion, the printed wiring board having both first and second substantially planar surfaces that are substantially parallel to each other and at least one filled hole extending from the first surface to the second surface.

4. (Previously Amended) A system comprising:
a scavenging blade;
a printed wiring board receiving portion; and
a movement mechanism adapted to move the scavenging blade and printed wiring board receiving portion relative to each other wherein:
the system is adapted to remove fill material which accumulates on the blade during the relative movement of the scavenging bladed and printed wiring board;
the system comprises a printed wiring board positioned on the printed wiring board receiving portion, the printed wiring board having both first and second

substantially planar surfaces that are substantially parallel to each other and at least one filled hole extending from the first surface to the second surface; and the scavenging blade is positioned adjacent to the first surface, between a first end and a second end of the printed wiring board, and divides the first surface into a first area and second area, wherein the first action comprises at least one hole containing fill material extending outward from the printed wiring board for a distance substantially greater than the distance separating the scavenging blade from the printed wiring board, and the second area comprises a plurality of holes containing fill material, none of which have fill material extending outward from the printed wiring board for a distance substantially greater than the distance separating the scavenging blade from the printed wiring board.

5. (Original) The system of claim 1 further comprising a filling mechanism wherein the scavenging blade is not part the filling mechanism.

6. (Original) The system of claim 5 wherein the scavenging blade moves independently from the filling mechanism.

7. (Original) The system of claim 5 wherein the scavenging blade is coupled to the filling mechanism.

8. (Original) The system of claim 5 wherein the filling mechanism is a squeegee or pressure head.

9. (Previously Amended) A system comprising:

a scavenging blade;

a printed wiring board receiving portion; and

a movement mechanism adapted to move the scavenging bladed and printed wiring board receiving portion relative to each other;

wherein the scavenging blade is polished, flexible, and sharpened along at least one edge such that it has a width less than or equal to approximately .003 inches.

10. (Previously Amended) The system of claim 9 wherein the system further comprises:

two guided rails extending along opposite sides of the receiving portion;

a crossbar coupled to two bearing blocks with one of the two bearing blocks being slideably coupled one of the two guide rails and, the other of the two bearing blocks being slideably coupled to the other guide rail and;

a clamping device clamping the scavenging bladed to the crossbar.

11. (Original) The system of claim 10 wherein the blades is pivotably coupled to the two guide rails.

12. (Currently Amended) A ~~The~~ system to remove ~~of claim 1 wherein the system is an~~ excess fill material ~~removal system~~ comprising:

a scavenging blade adapted to shear off fill material and promote uniform planarization by at least partially avoiding fill material dish-down into any fill holes caused by removal of excess fill material;

a printed wiring board receiving portion;

a movement mechanism adapted to move the scavenging blade and printed wiring board receiving portion relative to each other; and,

wherein the scavenging blade is positioned to move between a printed wiring board positioned in the receiving portion and at least some excess fill material on the printed wiring.

13. (Currently Amended) The system of claim 12 wherein the system is adapted to push a leading edge of the scavenging blade along a surface of printed wiring board to remove excess fill material from the printed wiring board.

14. (Original) The system of claim 13 wherein pushing the leading edge of the blade results from moving the printed wiring board relative to the bladed.